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S/N 09/897,320

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: George Hsieh
Serial No.: 09/897,320
Filed: June 29, 2001
Title: USING THE WAVE SOLDERING PROCESS TO ATTACH MOTHERBOARD
CHIPSET HEAT SINKS

Examiner: Unknown
Group Art Unit: 2835
Docket: 884.462US1

PATENT RECEIVED
MAR - 5 2002
TC 2800 MAIL ROOM

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant further request that a copy of the 1449 form, initialled by the Examiner to indicate that all listed citations have been considered, be returned with the next official communication.

Under 37 C.F.R. §1.97(b)(3), it is believed that no fee or certificate is required with this Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge any additional fees or credit any overpayment to Account No. 19-0743.

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

GEORGE HSIEH

By his Representatives,

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Date Feb. 14, 2002

By Ann M. McCrackin

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CERTIFICATE UNDER 37 C.F.R. § 1.97. The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 14 day of February, 2002.

ANN MCCRACKIN
Name

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Signature